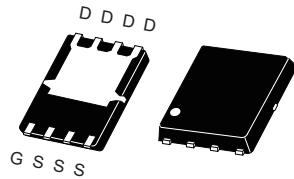


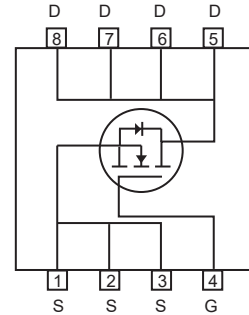
## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 40V, 113A,  $R_{DS(ON)} = 3.2m\Omega$  @ $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 4.8m\Omega$  @ $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability.
- RoHS compliant.
- Surface mount Package.



P-PAK 5X6



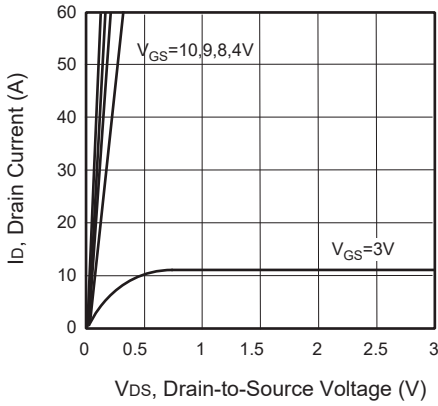
### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D @ R_{\theta JA}$	34	A
Drain Current-Continuous	$I_D @ R_{\theta JC}$	113	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{\theta JA}$	136	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{\theta JC}$	452	A
Maximum Power Dissipation	$P_D$	65	W
Single Pulsed Avalanche Energy <sup>e</sup>	$E_{AS}$	288	mJ
Single Pulsed Avalanche Current <sup>e</sup>	$I_{AS}$	24	A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

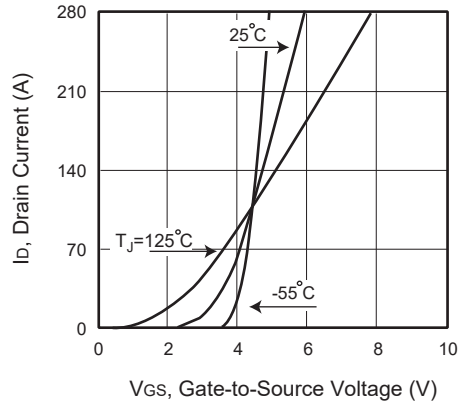
### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.9	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	20	$^\circ C/W$

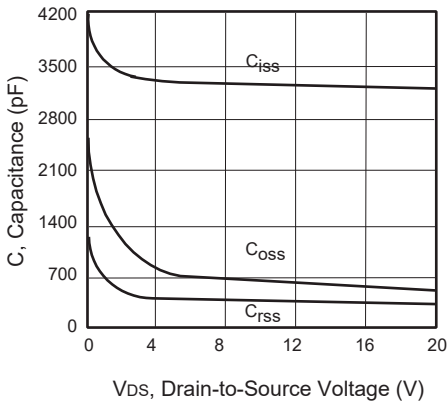




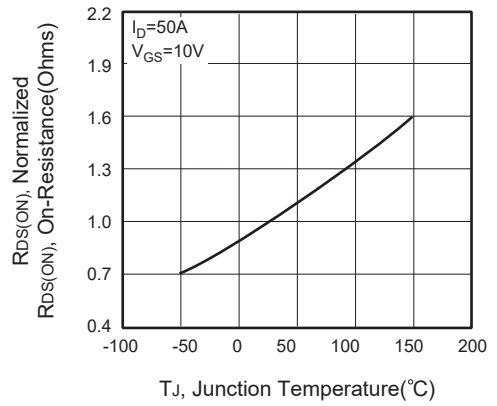
**Figure 1. Output Characteristics**



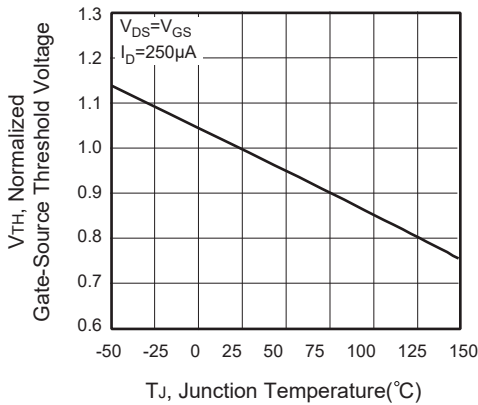
**Figure 2. Transfer Characteristics**



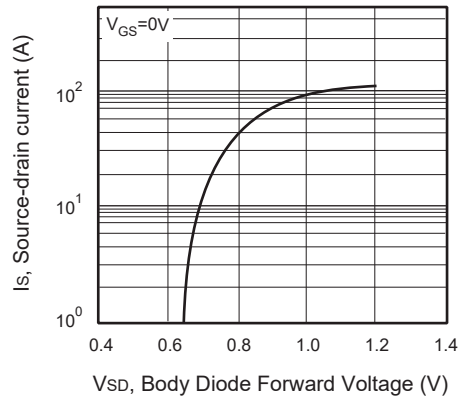
**Figure 3. Capacitance**



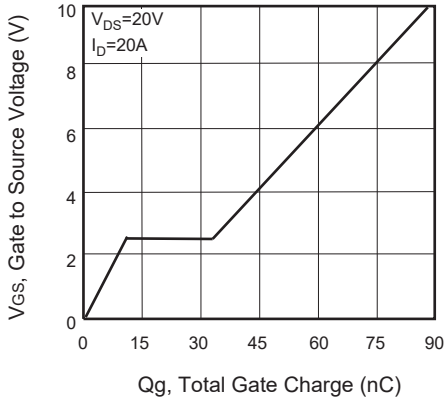
**Figure 4. On-Resistance Variation with Temperature**



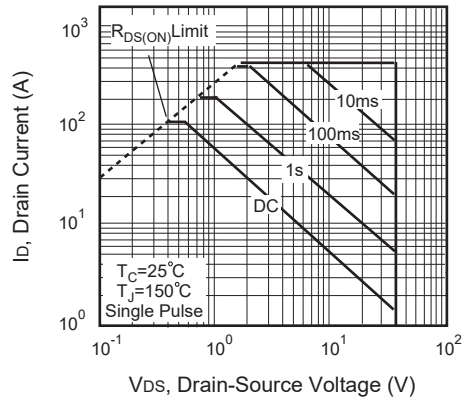
**Figure 5. Gate Threshold Variation with Temperature**



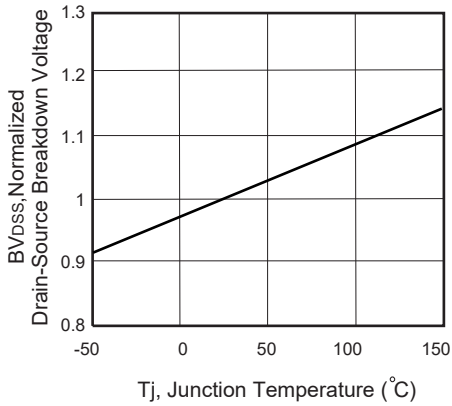
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



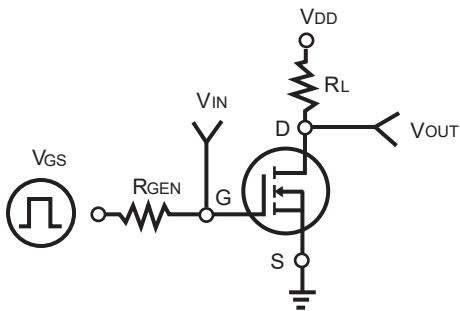
**Figure 7. Gate Charge**



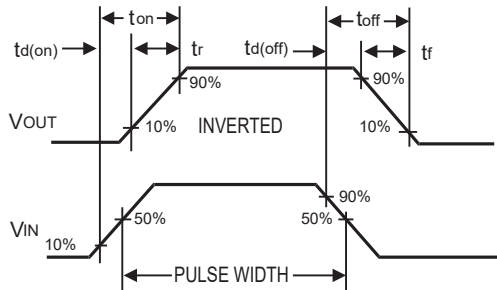
**Figure 8. Maximum Safe Operating Area**



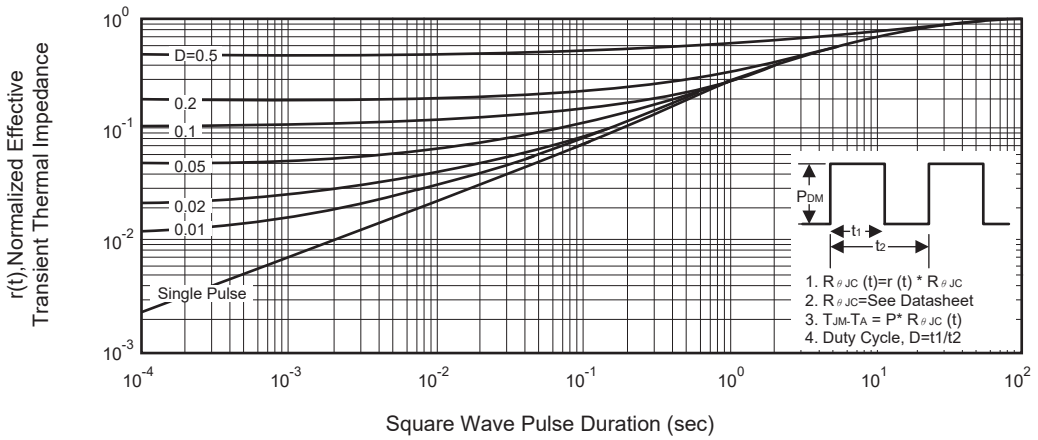
**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**



**Figure 12. Normalized Thermal Transient Impedance Curve**